



### 30V P-Channel Enhancement Mode MOSFET

Voltage -30 V Current -2.9A

#### **Features**

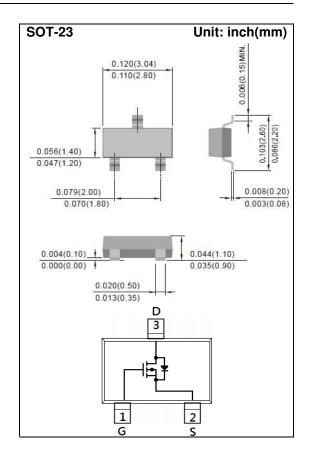
- $R_{DS(ON)}$ ,  $V_{GS}$ @-10V,  $I_{D}$ @-2.9A<110m $\Omega$
- $R_{DS(ON)}$ ,  $V_{GS}$ @-4.5V,  $I_{D}$ @-1.9A<150m $\Omega$
- Advanced Trench Process Technology
- Specially Designed for Switch Load, PWM Application, etc.
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 Standard

#### **Mechanical Data**

• Case: SOT-23 Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.0003 ounces, 0.0084 grams



### **Maximum Ratings and Thermal Characteristics** (T<sub>A</sub>=25 °C unless otherwise noted)

PARAMET	SYMBOL	LIMIT	UNITS		
Drain-Source Voltage	$V_{DS}$	-30	V		
Gate-Source Voltage	$V_{GS}$	<u>+</u> 20			
Continuous Drain Current (Note 4)		I <sub>D</sub>	-2.9	A	
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	-11.6		
Power Dissipation	T <sub>a</sub> =25°C	P <sub>D</sub>	1.25	W	
	Derate above 25°C		10	mW/°C	
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~150	°C	
Typical Thermal Resistance					
- Junction to Ambient (Note 3,4)	$R_{\theta JA}$	100	°C/W		





# **Electrical Characteristics** (T<sub>A</sub>=25 °C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS			
Static									
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-30	-	-	V			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=-250uA$	-1	-1.31	-2.1				
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-2.9A	-	92	110	mΩ			
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1.9A	-	120	150				
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ =-30V, $V_{GS}$ =0V	-	-	-1	uA			
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	<u>+</u> 100	nA			
Dynamic (Note 5)									
Total Gate Charge	$Q_g$	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	-	9.8	-	nC			
Gate-Source Charge	$Q_gs$	V <sub>DS</sub> =-15V, I <sub>D</sub> =-2.9A, V <sub>GS</sub> =-10V <sup>(Note 1,2)</sup>	-	1.5	-				
Gate-Drain Charge	$Q_gd$	V <sub>GS</sub> =-10V	-	2.2	-				
Input Capacitance	Ciss	\/ 45\/ \/ 0\/	-	396	-	pF			
Output Capacitance	Coss	$V_{DS}$ =-15V, $V_{GS}$ =0V, $f$ =1MHZ	-	47	-				
Reverse Transfer Capacitance	Crss		-	36	-				
Turn-On Delay Time	td <sub>(on)</sub>	$V_{DD}$ =-15V, $I_{D}$ =-2.9A, $V_{GS}$ =-10V, $R_{G}$ =6 $\Omega$ (Note 1,2)	-	5	-				
Turn-On Rise Time	tr		-	30	-				
Turn-Off Delay Time	td <sub>(off)</sub>		-	25	-				
Turn-Off Fall Time	tf		-	8	-				
Drain-Source Diode	Drain-Source Diode								
Maximum Continuous Drain-Source				-	-1.5	А			
Diode Forward Current	I <sub>S</sub>								
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V	-	-0.77	-1.2	V			

#### NOTES:

- 1. Pulse width<300us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. R<sub>OJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper.
- 4. The maximum current rating is package limited.
- 5. Guaranteed by design, not subject to production testing.





#### **TYPICAL CHARACTERISTIC CURVES**

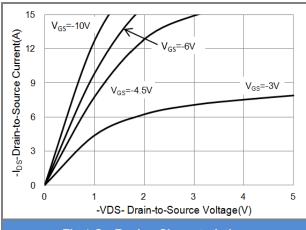
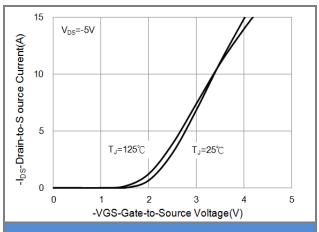


Fig.1 On-Region Characteristics



**Fig.2 Transfer Characteristics** 

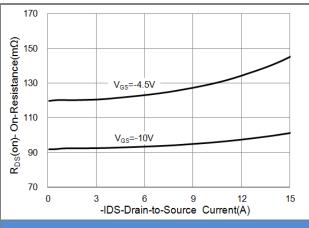


Fig.3 On-Resistance vs. Drain Current

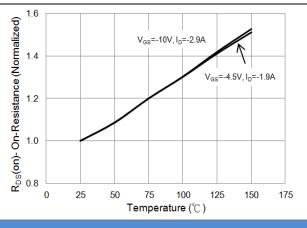
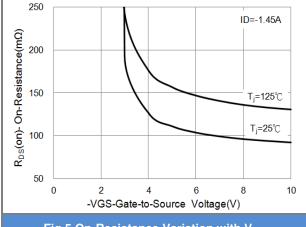
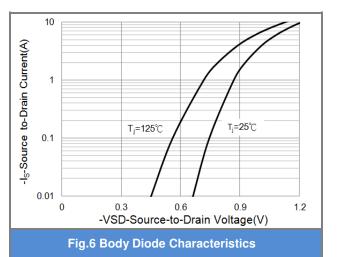


Fig.4 On-Resistance vs. Junction temperature







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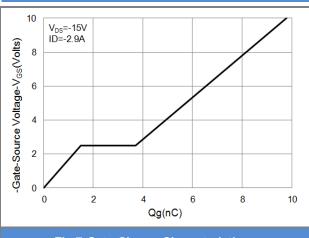


Fig.7 Gate-Charge Characteristics

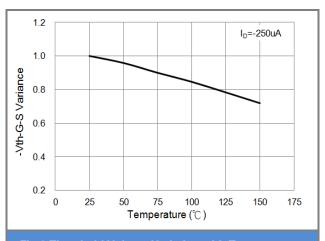


Fig.8 Threshold Voltage Variation with Temperature

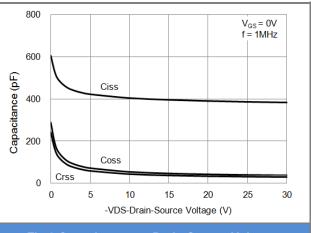


Fig.9 Capacitance vs. Drain-Source Voltage

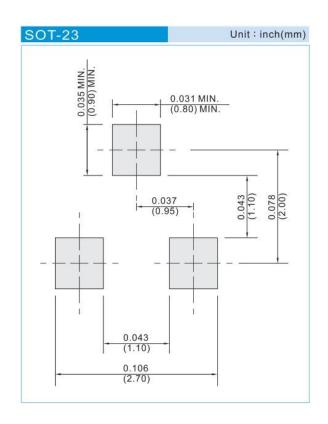




### **Part No Packing Code Version**

Part No Packing Code	Package Type	Packing Type	Marking	Version
PJA3409-AU_R1_000A1	SOT-23	3K pcs / 7" reel	A09	Halogen free

### **Packaging Information & Mounting Pad Layout**







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